

# **PRODUCT SPECIFICATION**

# MONO LCD MODULE MODEL: G1206B5FSW7B-J0 Ver:1.0

- < >> Preliminary Specification
- < ◆> Finally Specification

CUSTOMER'S APPROVAL									
CUSTOMER:									
SIGNATURE: DATE:									

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	Ву

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# **Revision Status**

Version	Revise Date	Page	Content	Modified By
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# 1. Features

The features of LCD are as follows

\* Display mode :FSTN/Transflective/Positive

\* Drive IC : AIP31107&AIP31108

\* Interface Input Data : 8-Bits

\* Driving Method : 1/64Duty, 1/6 Bias

\* Viewing Direction : 12 O'clock \* Backlight : LED (White)

\*Sample NO. : G1206B5FSW7B-J0\_01/20130119

## 2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	93(W) x 70(H) x 13max(D)	mm
Number of Dots	128x64 Dots	
Viewing Area	70.2(W) x 38.8(H)	mm
Activity Area	66.52(W)x33.24(H)	mm
Dot Size	0.48(W) x 0.48(H)	mm
Dot Pitch	0.52(W) x0.52(H)	mm

## 3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTR MAZIMUM RATINGS (Ta = 25 °C)

Hom	Symbol	Sta			
ltem	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	V <sub>DD</sub> – V <sub>ss</sub>	0.3	-	7.0	V
Supply Voltage For LCD Drive	V <sub>OP</sub> = V <sub>DD</sub> - V <sub>0</sub>	VEE-0.3	-	V <sub>DD</sub> +0.3	V
Input Voltage	Vin	-	-	-	V
Operating Temp.	Тор	-20	-	+70	°C
Storage Temp.	Tst	-30	-	+80	°C

<sup>\*.</sup> NOTE: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

3-2 ELECTRICAL CHARACTERISTICS

Item		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic supply	Voltage	V <sub>DD</sub> – V <sub>ss</sub>		4.5	5	5.5	V
LCD Dri	LCD Drive		Ta = 25 °C	8.1	8.4	8.7	V
Input Voltage	"H" Level	V <sub>IH</sub>	V <sub>DD</sub> =5V ± 10%	0.7Vdd	-	VDD	V
	"L" Level	V <sub>IL</sub>		0	-	0.3 VDD	V
Frame Frequency		f <sub>FLM</sub>		-	78	-	Hz
Current Cons	umption	I <sub>DD</sub>		-	13	-	mA

## 3-3. BACKLIGHT

## 3-3-1. Absolute Maximum Ratings

Item	Symbol	Symbol Condition		Тур.	Max.	Unit
Forward Current	IF		-	60	80	mA
Reverse Voltage	VR	Ta = 25 °C	-	-	5	<b>V</b>
Power Dissipation	PD		-	-	264	mW

## 3-3-2. Electrical-optical Characteristics

ltem	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Current	IF		-	60	-	mA
Average Luminous Intensity	lv	VF=3.1V Ta = 25 °C	200	-	-	cd/m <sup>2</sup>
Calar Caardinata	Х		0.26	0.30	0.33	n.m.
Color Coordinate	Y		0.26	0.30	0.33	nm
Lifetime		If=60mA	18000	20000	-	Hours

## The brightness is measured without LCD panel

For operation above 25°C, The Ifm Ifp &Pd must be derated, the current derating is -0.36mA/°C for DC drive and -0.86 mA/°C for Pulse drive, the Power dissipation is -0.75mW/°C.

The product working current must not more than the  $60\,\%$  of the Ifm or Ifp according to the working temperature.

Backlight lifetime means luminance value larger than half of the original after 20000 hours' continuous working.

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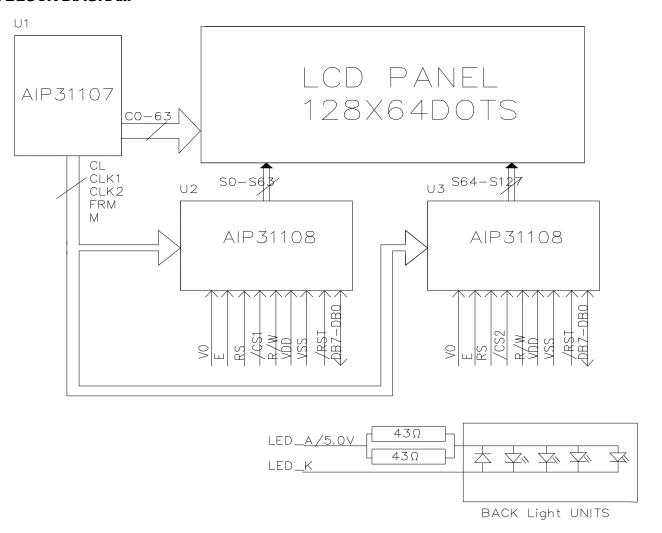
# 4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

## 4-1. INTERFACE PIN FUNCTION DESCRIPTION

PIN NO.	SYMBOL	FUNCIONS
1	VSS	Ground (0V)
2	VDD	Supply voltage for logical circuit(5V)
3	V0	Supply voltage for LCD driving
4	RS	Select register signal
5	R/W	H: Data Read (LCM to MPU) ; L: Data Write (MPU to LCM)
6	E	Enable Signal
7~14	DB0~DB7	Data bus line
15	/CS1	Chip Selection Signal for U2
16	/CS2	Chip Selection Signal for U3
17	/RST	Reset (Active "LOW")
18	VEE	Negative voltage supply pin
19	LED_A	Backlight (+5V)
20	LED_K	Backlight (-)

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## 4-2. BLOCK DIAGRAM



# **5. TIMING CHARACTERISTICS**

Characteristic	Symbol	Min	Тур	Max	Unit
E Cycle	tc	1000	_	_	ns
E High Level Width	tWH	450	_	_	ns
E Low Level Width	tWL	450	_	_	ns
E Rise Time	tR	_	_	25	ns
E Fall Time	tF	_	_	25	ns
Address Set-Up Time	tASU	140	_	_	ns
Address Hold Time	tAH	10	_	_	ns
Data Set-Up Time	tDSU	200	_	_	ns
Data Delay Time	tD	_	_	320	ns
Data Hold Time (Write)	tDHW	10	_	_	ns
Data Hold Time (Read)	tDHR	20	_	_	ns

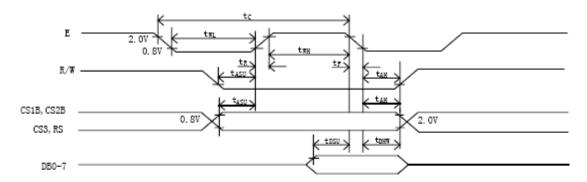


Fig 3. MPU write timing

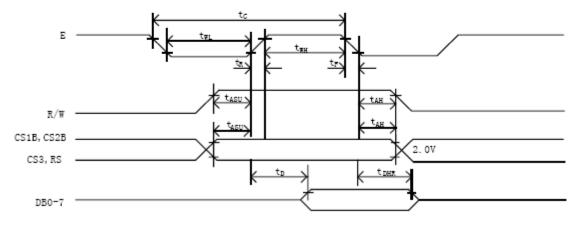


Fig 4. MPU Read timing

# **6. INSTRUCTION SET**

The display control instructions control the internal state of the AIP31108. Instruction is received from MPU to AIP31108 for the display control. The following table shows various instructions.

MPU to AIP3	11001	OI THE	uispiay	COITH OI.	THE IO	lowing t	able Sill	JWS Va	illous i	HSUUCI	ions.
Instruction	RS	R/ W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function
Display ON/OFF	L	L	L	L	Н	Н	Н	н	н	L/H	Controls the display on or off. Internal status and display RAM data is not affected. L:OFF, H:ON
Set Address (Y address)	L	L	L	Н	Y addre	ss (0~63	)	•			Sets the Y address in the Y address counter.
Set Page ( X address)	L	L	Н	L	Н	Н	Н	Page (	0-7)		Sets the X address at the X address register.
Display Start Line (Z address)	L	L	Н	Н	Display	start line	(0-63)				Indicates the display data RAM displayed at the top of the screen.
Status Read	L	н	busy	L	On/off	reset	L	L	L	L	Read status. BUSY L: Ready H: In operation ON/OFF L: Display ON H: Display OFF RESET L: Normal H: Reset
Write Display Data	Н	L	Write D	ata							Writes data (DB0:7) into display data RAM. After writing instruction, Y address is increased by 1 automatically.
Read Display Data	Н	Н	Read D	ata							Reads data (DB0:7) from display data RAM to the data bus.

1. Display On/Off

		• •							
RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	1	1	1	D

The display data appears when D is 1 and disappears when D is 0.

Though the data is not on the screen with D=0, it remains in the display data RAM.

Therefore, you can make it appear by changing D=0 into D=1.

2. Set Address (Y Address)

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

Y address (AC0 ~ AC5) of the display data RAM is set in the Y address counter.

An address is set by instruction and increased by 1 automatically by read or write operations of display data.

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3. Set Page (X Address)

	0-1								
RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	1	1	AC2	AC1	AC0

X address(AC0 ~ AC2) of the display data RAM is set in the X address register.

Writing or reading to or from MPU is executed in this specified page until the next page is set.

4. Display Start Line (Z Address)

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	AC5	AC4	AC3	AC2	AC1	AC0

Z address (AC0  $\sim$  AC5) of the display data RAM is set in the display start line register and displayed at the top of the screen. When the display duty cycle is 1/64 or others(1/32  $\sim$  1/64), the data of total line number of LCD screen, from the line specified by display start line instruction, is displayed.

#### 5. Status Read

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	BUSY	0	ON/OFF	RESET	0	0	0	0

#### BUSY

When BUSY is 1, the Chip is executing internal operation and no instructions are accepted. When BUSY is 0, the Chip is ready to accept any instructions.

#### ON/OFF

When ON/OFF is 1, the display is on.

When ON/OFF is 0, the display is off.

#### RESET

When RESET is 1, the system is being initialized. In this condition, no instructions except status read can be accepted.

When RESET is 0, initializing has finished and the system is in the usual operation condition.

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6. Write Display Data

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	D7	D6	D5	D4	D3	D2	D1	D0

Writes data (D0 ~ D7) into the display data RAM.

After writing instruction, Y address is increased by 1 automatically.

7. Read Display Data

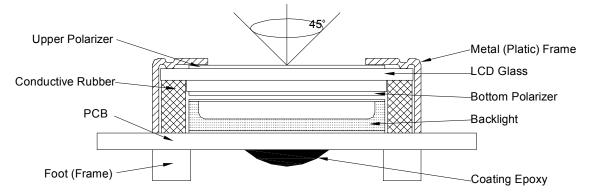
RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	1	D7	D6	D5	D4	D3	D2	D1	D0

Reads data (D0 ~ D7) from the display data RAM.

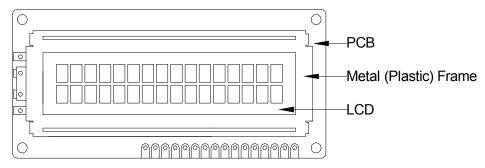
After reading instruction, Y address is increased by 1 automatically.

## 7. QUALITY SPECIFICATIONS

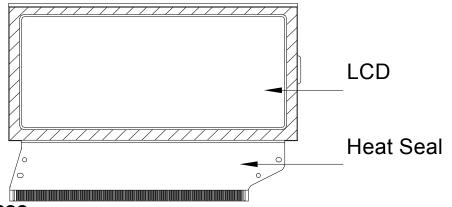
- 7-1. LCM Appearance and Electric inspection Condition
  - 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



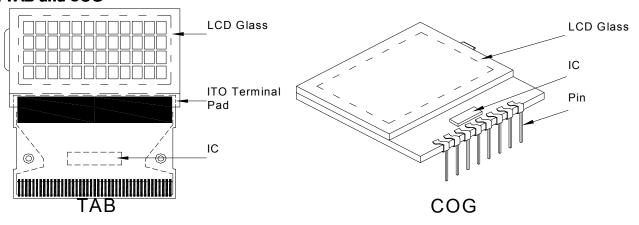
- 2. View Angle: with in 45° around perpendicular line.
- 7-2. Definition
  - 1. COB



#### 2. Heat Seal



## 3. TAB and COG



## 7-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E ( || ) ordinary single inspection is used.

2.Acceptance

Major defect: AQL = 0.65% Minor defect: AQL = 1.5%

## 7-4. Criteria

## 1.COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup>	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

## **2.SMT**

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift  component soldering pad  X  D  Y	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt component soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD ← PCB	θ ≤ 20°	Reject

## 3. Metal (Plastic) Frame

Defect	Inspection Item	li	nspection Standa	rds	
Major	Crack / breakage	Any	/where	Reject	
		W	L	Acceptable of Scratch	
		w<0.1mm	Any	Ignore	
		0.1 <u>&lt;</u> w<0.2mm	L <u>&lt;</u> 5.0mm	2	
Minor	Frame Scratch	0.2 <u>&lt;</u> w<0.3mm	L <u>&lt;</u> 3.0mm	1	
		w <u>&gt;</u> 0.3mm	Any	0	
		with distance gi	e criteria applicabl reater than 5mm. on the back sid ignored .		
				Acceptable of Dents / Pricks	
		Φ<	2		
	Frame Dent , Prick	1.0<	1		
Minor	$\Phi = \frac{\Gamma + M}{2}$	1.5ı	mm<Ф	0	
	2	/ pricks with dis	e criteria applicable tance greater than rick on the back s ignored	5mm	
Minor	Minor Frame Deformation Exceed the dimension of drawing				
Minor	Metal Frame Oxidation		Any rust		

## 4. Flexible Film Connector (FFC)

Defect	Inspection Item	Inspection Standa	rds
Minor	Tilted soldering	Within the angle +5°	Acceptable
Minor	Uneven solder joint /bump		Reject
		Expose the conductive line	Reject
Minor	Hole $\Phi = \frac{L + W}{2}$	Ф > 1.0mm	Reject
Minor	Position shift	Y > 1/3D	Reject
IVIII IOI	- <del> </del>	X > 1/2Z	Reject

## 5. Screw

Defect	Inspection Item	Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

## 6. Heatseal . TCP . FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	Ф> 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
	Position shift	Y > 1/3D	Reject
Minor		X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards				
		Acceptable number of units				
		Ф <b>≤</b> 0.10mm	Ignore			
Minor	LED dirty, prick	0.10<⊕ <u>&lt;</u> 0.15mm	2			
		0.15<⊕ <u>&lt;</u> 0.2mm	1			
		Ф>0.2mm	0			
		The distance between any two spots should be ≥5mm Any spot/dot/void outside of viewing area is acceptable				
Minor	Protective film tilt	t Not fully cover LCD				
Major	COG coating	Not fully cover ITO circuit				

8. Electric Inspection

Defect	Inspection Item	Inspection Standards			
Major	Short		Reject		
Major	Open		Reject		

## 9. Inspection Specification of LCD

								JUC. IN			
Defect	Insp	ect Item	Inspection Standards								
		* Glass Scratch	W	W <sub>5</sub>	W <u>&lt;</u> 0.03		0.03 <w<u>&lt;0.05</w<u>		V>0.05		
		* Polarizer Scratch	L	L	_<5	L<3			Any		
Minor	<b>Linear Defect</b>	* Fiber and Linear	ACC.		1	1 1		Reject			
		material	Note	L is the length and W is the width of the				defect			
		* Foreign material		Φ <b>&lt;</b> 0.1	0.1<⊕≤0	<b>0.15&lt; 0.15 0.15</b>		.2	Φ>0.2		
	Black Spot and Polarizer Pricked	between glass and polarizer or glass		3EA / 100mm²	2		1		0		
Minor		* Polarizer hole or protuberance by	Note	$\Phi$ is the average diameter of the defect. Distance between two defects > 10mm.				•			
		external force  * Unobvious	Φ	Φ<0.3 0.3<Φ<0.5 0.5<Φ				<b>5&lt;</b> Φ			
		transparant foreign	_	Ψ3	20.3	0.5	·Ψ <u>&gt;</u> υ.5	<b>U</b> .	<b>3</b> ~Ψ		
		transparant foreign	ACC.		•		•		_		
			Φ	Ф <b>≤0.10</b>	0.10<⊕≤	0.20	<b>0.20</b> <Φ <u>9</u>	≤0.25	⊕>0.25		
		w	ACC. NO.	3EA / 100mm²	2		1		0		
				W is more than 1/2 segment			ent width	th Reject			
		W T	Note	$\Phi = \frac{\Gamma + M}{2}$ Distance between tw		wo de					
			Φ	Φ≤0.10	0.10<⊕≤0.20 0.20<⊕≤		≤0.25	Φ>0.25			
	Protuberant Segment	$\Phi = (L + W)/2$	W	Glue	W <u>&lt;</u> 1/2 Seg W<0.2		W <u>&lt;</u> 1/2 Seg W<0.2		Ignore		
Minor			ACC. NO.	3EA / 100mm²	2	_	1	<b>-</b>	0		
	Assembly Mis-alignm		1. Seg	ment			l		I		
Minor			E	B <u>&lt;</u> 0.4mm		0.4 <b<u>&lt;1.0mm B&gt;1</b<u>		.0mm			
			В	-A B	-A<1/2B	В-	A<0.2	B- <b>A</b>	<b>&lt;0.25</b>		
			Juc	udge Acceptable Acceptable Acce			eptable				
			2. Dot	Matrix							
			Defo	rmation>2	2°				Reject		
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"								

# 8. RELIABILITY

NO.	Item	Condition	Criterion
1	High Temperature Operating	70℃, 96Hrs	
2	Low Temperature Operating	-20℃, 96Hrs	
3	High Humidity	40°C, 90%RH, 96Hrs	
4	High Temperature Storage	80℃, 96Hrs	
5	Low Temperature Storage	-30℃, 96Hrs	No defect in cosmetic and
6	Vibration	Random wave  10 ~ 100Hz  Acceleration: 2g  2 Hrs per direction(X,Y,Z)	operational function allowable.  Total current Consumption should be below double of initial value.
7	Thermal Shock	-20°C to25°C to70°C (60Min) (5Min) (60Min) 16Cycles	
8	ESD Testing	Contract Discharge Voltage: +1 ~ 4kV and –1 ~ –4kV	There will be discharged ten times at every discharging
		Air Discharge Voltage: +1 ~ 6kV and –1 ~ -6kV	voltage cycle. The voltage gap is 1kV.

Note: 1) Above conditions are suitable for our company standard products.
2) For restrict products, the test conditions listed as above must be revised.

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# 9. HANDLING PRECAUTION

## (1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

## (2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water- Ketone- Aromatics

#### (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

## (4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

#### (5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

## (6) Storage

- In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.
- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

#### (7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

- When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

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## 10. OUTLINE DIMENSION

